

CYPRESS

PRELIMINARY

CY2273

Cypress Semiconductor Corporation • 3901 North First Street • San Jose • CA 95134 • 408-943-2600
January 30, 1997 - Revised March 24, 1997



Pin Configurations (continued)

AV _{DD}	1	48	V _{DDQ3}
REF0	2	47	USBCLK
V _{SS}	3	46	SEL1
XTALIN	4	45	V _{SS}
XTALOUT	5	44	CPUCLK0
V _{DDQ3}	6	43	CPUCLK1
PCICLK_F	7	42	V _{DDCPU}
PCICLK0	8	41	CPUCLK2
V _{SS}	9	40	CPUCLK3
PCICLK1	10	39	V _{SS}
PCICLK2	11	38	SDRAM0
PCICLK3	12	37	SDRAM1
AGP0	13	36	V _{DDQ3}
V _{DDQ3}	14	35	SDRAM2
AGP1	15	34	SDRAM3
V _{SS}	16	33	V _{SS}
SDRAM11	17	32	SDRAM4
SDRAM10	18	31	SDRAM5/PWR_DWN
V _{DDQ3}	19	30	V _{DDQ3}
SDRAM9	20	29	SDRAM6/CPU_STOP
SDRAM8	21	28	SDRAM7/PCI_STOP
V _{SS}	22	27	V _{SS}
SDATA	23	26	SEL0
SCLK	24	25	MODE

USBCLK	1	48	V _{DDQ2}
REF0	2	47	IOAPIC
V _{SS}	3	46	SEL0
XTALIN	4	45	V _{SS}
XTALOUT	5	44	CPUCLK0
V _{DDQ3}	6	43	CPUCLK1
PCICLK_F	7	42	V _{DDCPU}
PCICLK0	8	41	CPUCLK2
V _{SS}	9	40	CPUCLK3
PCICLK1	10	39	V _{SS}
PCICLK2	11	38	SDRAM0
PCICLK3	12	37	SDRAM1
PCICLK4	13	36	V _{DDQ3}
V _{DDQ3}	14	35	SDRAM2
PCICLK5	15	34	SDRAM3
V _{SS}	16	33	V _{SS}
SDRAM11	17	32	SDRAM4
SDRAM10	18	31	SDRAM5/PWR_DWN
V _{DDQ3}	19	30	V _{DDQ3}
SDRAM9	20	29	SDRAM6/CPU_STOP
SDRAM8	21	28	SDRAM7/PCI_STOP
V _{SS}	22	27	V _{SS}
AV _{DD}	23	26	MODE
SDATA	24	25	SCLK

Pin Summary

Name	Pins (-1, -2)	Pins (-3)	Description
V _{DDQ3}	6, 14, 19, 30, 36, 48	6, 14, 19, 30, 36	3.3V Digital voltage supply
V _{DDQ2}	N/A	48	IOAPIC Digital voltage supply, 2.5V
V _{DDCPU}	42	42	CPU Digital voltage supply, 2.5V or 3.3V
AV _{DD}	1	23	Analog voltage supply, 3.3V
V _{SS}	3, 9, 16, 22, 27, 33, 39, 45	3, 9, 16, 22, 27, 33, 39, 45	Ground
XTALIN ^[1]	4	4	Reference crystal input
XTALOUT ^[1]	5	5	Reference crystal feedback
SDRAM7/ PCI_STOP	28	28	SDRAM clock output. Also, active low control input to stop PCI clocks, enabled when MODE is Low
SDRAM6/ CPU_STOP	29	29	SDRAM clock output. Also, active low control input to stop CPU clocks, enabled when MODE is Low.
SDRAM5/ PWR_DWN	31	31	SDRAM clock output. Also, active low control input to power down device, enabled when MODE is Low.
SDRAM[0:4].[8:11]	38, 37, 35, 34, 32, 21, 20, 18, 17	38, 37, 35, 34, 32, 21, 20, 18, 17	SDRAM clock outputs
SEL0	26	46	CPU frequency select input, bit 0 (See table below.)
SEL1	46	N/A	CPU frequency select input, bit 0 (See table below.)
CPUCLK[0:3]	44, 43, 41, 40	44, 43, 41, 40	CPU clock outputs
PCICLK[0:5]	8, 10, 11, 12, 13, 15	8, 10, 11, 12, 13, 15	PCI clock outputs, at one-half the CPU frequency. Pins 13 and 15 are AGP clocks in -2
PCICLK_F	7	7	Free-running PCI clock output
IOAPIC	N/A	47	IOAPIC clock output
REF0	2	2	3.3V Reference clock output
USBCLK	47	1	USB Clock output
SDATA	23	24	Serial data input for serial configuration port
SCLK	24	25	Serial clock input for serial configuration port
MODE	25	26	Mode Select pin for enabling power management features

Note:

- For best accuracy, use a parallel-resonant crystal, C_{LOAD} = 18 pF.

Function Table

SEL1	SEL0	CPU/PCI Ratio	CPUCLK[0:3] SDRAM[0:11]	PCICLK[0:5] PCICLK_F	AGP (-2 Only)	REF0 IOAPIC	USBCLK
0	0	2	60.0 MHz	30.0 MHz	60.0 MHz	14.318 MHz	48 MHz
0	1	2	66.67 MHz	33.33 MHz	66.66 MHz	14.318 MHz	48 MHz
1	0	2.5	75.0 MHz	30.0 MHz	60.0 MHz	14.318 MHz	48 MHz
1	1	2.5	83.33 MHz	33.33 MHz	66.66 MHz	14.318 MHz	48 MHz

Actual Clock Frequency Values

Clock Output	Target Frequency (MHz)	Actual Frequency (MHz)	PPM
CPUCLK	66.67	66.654	-195
CPUCLK	60.0	60.0	0
CPUCLK	75.0	75.0	0
CPUCLK	83.33	83.138	-1947
USBCLK	48.0	48.008	167

CPU and PCI Clock Driver Strengths

- Matched impedances on both rising and falling edges on the output drivers
- Output impedance: 25Ω (typical) measured at 1.5V.

Power Management Logic^[2] - Active when MODE pin is held 'LOW'

CPU_STOP	PCI_STOP	PWR_DWN	CPUCLK	PCICLK	PCICLK_F	Other Clocks	Osc.	PLLs
X	X	0	Low	Low	Stopped	Stopped	Off	Off
0	0	1	Low	Low	Running	Running	Running	Running
0	1	1	Low	33/30 MHz	Running	Running	Running	Running
1	0	1	60/66/75/83 MHz	Low	Running	Running	Running	Running
1	1	1	60/66/75/83 MHz	30/33/30/33 MHz	Running	Running	Running	Running

Serial Configuration Map

- The Serial bits will be read by the clock driver in the following order:

Byte 0 - Bits 7, 6, 5, 4, 3, 2, 1, 0

Byte 1 - Bits 7, 6, 5, 4, 3, 2, 1, 0

Byte N - Bits 7, 6, 5, 4, 3, 2, 1, 0

- Reserved and unused bits should be programmed to "0".
- I²C Address for the CY2273 is:

A6	A5	A4	A3	A2	A1	A0	R/W
1	1	0	1	0	0	1	----

Byte 0: Functional and Frequency Select Clock Register (1 = Enable, 0 = Disable)

Bit	Pin #	Description
Bit 7	--	(Reserved) drive to '0'
Bit 6	--	(Reserved) drive to '0'
Bit 5	--	(Reserved) drive to '0'
Bit 4	--	(Reserved) drive to '0'
Bit 3	--	(Reserved) drive to '0'
Bit 2	--	(Reserved) drive to '0'
Bit 1	--	Bit 1
Bit 0	--	Bit 0
		1 - Three-State
		0 - N/A
		1 - Testmode
		0 - Normal Operation

Select Functions

Functional Description	Outputs					USBCLK
	CPU	PCI, PCI_F	SDRAM	Ref	IOAPIC	
Three-State	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z
Test Mode ^[4]	TCLK/2 ^[3]	TCLK/4	TCLK/2	TCLK	TCLK	TCLK/2

Notes:

- AGP clocks are driven on PCICLK5 and PCICLK4 on -2 option. These clocks behave similar to the PCICLK_F output, in that they are free-running and stop only when the PWR_DWN pin is asserted. The frequency of the AGP clocks is as shown in the Function Table.
- TCLK supplied on the XTALIN pin in Test Mode.
- Valid only for SEL1=0

Byte 1: CPU Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Pin #	Description
Bit 7	47 (-1/-2) 1 (-3)	USBCLK
Bit 6	N/A	(Reserved) drive to '0'
Bit 5	N/A	(Reserved) drive to '0'
Bit 4	N/A	Not used - drive to '0'
Bit 3	40	CPUCLK3 (Active/Inactive)
Bit 2	41	CPUCLK2 (Active/Inactive)
Bit 1	43	CPUCLK1 (Active/Inactive)
Bit 0	44	CPUCLK0 (Active/Inactive)

Byte 3: SDRAM Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Pin #	Description
Bit 7	28	SDRAM7 (Active/Inactive)
Bit 6	29	SDRAM6 (Active/Inactive)
Bit 5	31	SDRAM5 (Active/Inactive)
Bit 4	32	SDRAM4 (Active/Inactive)
Bit 3	34	SDRAM3 (Active/Inactive)
Bit 2	35	SDRAM2 (Active/Inactive)
Bit 1	37	SDRAM1 (Active/Inactive)
Bit 0	38	SDRAM0 (Active/Inactive)

Byte 5: Peripheral Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Pin #	Description
Bit 7	N/A	(Reserved) drive to '0'
Bit 6	N/A	(Reserved) drive to '0'
Bit 5	N/A	(Reserved) drive to '0'
Bit 4	47	IOAPIC (Active/Inactive) (-3 ONLY)
Bit 3	N/A	(Reserved) drive to '0'
Bit 2	N/A	(Reserved) drive to '0'
Bit 1	N/A	(Reserved) drive to '0'
Bit 0	2	REF0 (Active/Inactive)

Byte 2: PCI Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Pin #	Description
Bit 7	--	(Reserved) drive to '0'
Bit 6	7	PCICLK_F (Active/Inactive)
Bit 5	15	PCICLK5 (Active/Inactive) (-1 and -3) AGP1 (Active/Inactive) (-2 only)
Bit 4	14	PCICLK4 (Active/Inactive) (-1 and -3) AGP0 (Active/Inactive) (-2 only)
Bit 3	12	PCICLK3 (Active/Inactive)
Bit 2	11	PCICLK2 (Active/Inactive)
Bit 1	10	PCICLK1 (Active/Inactive)
Bit 0	8	PCICLK0 (Active/Inactive)

Byte 4: SDRAM Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Pin #	Description
Bit 7	N/A	Not used - drive to '0'
Bit 6	N/A	Not used - drive to '0'
Bit 5	N/A	Not used - drive to '0'
Bit 4	N/A	Not used - drive to '0'
Bit 3	17	SDRAM11
Bit 2	18	SDRAM10
Bit 1	20	SDRAM9
Bit 0	21	SDRAM8

Byte 6: Reserved, for future use

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Supply Voltage -0.5 to +7.0V

Input Voltage -0.5V to $V_{DD}+0.5$

Storage Temperature (Non-Condensing) ... -65°C to +150°C

Max. Soldering Temperature (10 sec) +260°C

Junction Temperature +150°C

Package Power Dissipation 1W

Static Discharge Voltage >2000V
(per MIL-STD-883, Method 3015)

Operating Conditions^[5]

Parameter	Description	Min.	Max.	Unit
AV_{DD} , V_{DDQ3}	Analog and Digital Supply Voltage	3.135	3.465	V
V_{DDCPU}	CPU Supply Voltage	2.375 3.135	2.9 3.465	V
V_{DDQ2}	IOAPIC Supply Voltage	2.375	2.9	V
T_A	Operating Temperature, Ambient	0	70	°C
C_L	Max. Capacitive Load on CPUCLK, USBCLK, IOAPIC PCICLK, AGP, SDRAM REF0	10 30, 20 20	20 30 45	pF
$f_{(REF)}$	Reference Frequency, Oscillator Nominal Value	14.318	14.318	MHz

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		Min.	Max.	Unit
V_{IH}	High-level Input Voltage	Except Crystal Inputs		2.0		V
V_{IL}	Low-level Input Voltage	Except Crystal Inputs			0.8	V
V_{OH}	High-level Output Voltage	$V_{DDCPU} = V_{DDQ2} = 2.375V$	$I_{OH} = 16\text{ mA}$ CPUCLK $I_{OH} = 18\text{ mA}$ IOAPIC	2.0		V
V_{OL}	Low-level Output Voltage	$V_{DDCPU} = V_{DDQ2} = 2.375V$	$I_{OL} = 27\text{ mA}$ CPUCLK $I_{OL} = 29\text{ mA}$ IOAPIC		0.4	V
V_{OH}	High-level Output Voltage	V_{DDQ3} , AV_{DD} , $V_{DDCPU} = 3.135V$	$I_{OH} = 16\text{ mA}$ CPUCLK $I_{OH} = 36\text{ mA}$ SDRAM $I_{OH} = 32\text{ mA}$ PCICLK $I_{OH} = 26\text{ mA}$ USBCLK $I_{OH} = 36\text{ mA}$ REF0	2.4		V
V_{OL}	Low-level Output Voltage	V_{DDQ3} , AV_{DD} , $V_{DDCPU} = 3.135V$	$I_{OL} = 27\text{ mA}$ CPUCLK $I_{OL} = 29\text{ mA}$ SDRAM $I_{OL} = 26\text{ mA}$ PCICLK $I_{OL} = 21\text{ mA}$ USBCLK $I_{OL} = 29\text{ mA}$ REF0		0.4V	V
I_{IH}	Input High Current	$V_{IH} = V_{DD}$		-10	+10	μA
I_{IL}	Input Low Current	$V_{IL} = 0V$			10	μA
I_{OZ}	Output Leakage Current	Three-state		-10	+10	μA
I_{DD}	Power Supply Current ^[6]	$V_{DD} = 3.465V$, $V_{IN} = 0$ or V_{DD} , Loaded Outputs, CPU clocks = 66.67 MHz			300	mA
I_{DD}	Power Supply Current ^[6]	$V_{DD} = 3.465V$, $V_{IN} = 0$ or V_{DD} , Unloaded Outputs			120	mA
I_{DDS}	Power-down Current	Current draw in power-down state			50	μA

Notes:

5. Electrical parameters are guaranteed with these operating conditions.

6. Power supply current will vary with number of outputs which are running. Therefore, power supply current can be calculated with the following formula: TBD

Switching Characteristics^[7]

Parameter	Output	Description	Test Conditions	Min.	Typ.	Max.	Unit
t ₁	All	Output Duty Cycle ^[8]	$t_1 = t_{1A} \div t_{1B}$	45	50	55	%
t ₂	CPUCLK, IOAPIC	CPU and IOAPIC Clock Rising and Falling Edge Rate	Between 0.4V and 2.0V, V _{DDCPU} = 2.5V Between 0.4V and 2.4V, V _{DDCPU} = 3.3V	1.0		4.0	V/ns
t ₂	PCICLK, AGP, REF0	PCI, AGP, REF0 Clock Rising and Falling Edge Rate	Between 0.4V and 2.4V	1.0		4.0	V/ns
t ₂	SDRAM	SDRAM Rising and Fall- ing Edge Rate	Between 0.4V and 2.4V	1.0		4.0	V/ns
t ₃	CPUCLK	CPU Clock Rise Time	Between 0.4V and 2.0V, V _{DDCPU} = 2.5V Between 0.4V and 2.4V, V _{DDCPU} = 3.3V	0.4 0.5		1.6 2.0	ns
t ₄	CPUCLK	CPU Clock Fall Time	Between 2.0V and 0.4V, V _{DDCPU} = 2.5V Between 2.4V and 0.4V, V _{DDCPU} = 3.3V	0.4 0.5		1.6 2.0	ns
t ₅	CPUCLK	CPU-CPU Clock Skew	Measured at 1.25V, V _{DDCPU} = 2.5V Measured at 1.5V, V _{DDCPU} = 3.3V		100	250	ps
t ₆	CPUCLK, PCICLK	CPU-PCI Clock Skew (-1, -2)	Measured at 1.25V for 2.5V clocks, and at 1.5V for 3.3V clocks	1.0	2.0	4.0	ns
t ₆	CPUCLK, PCICLK	CPU-PCI Clock Skew (-3)	Measured at 1.25V for 2.5V clocks, and at 1.5V for 3.3V clocks			0.5	ns
t ₇	CPUCLK, SDRAM	CPU-SDRAM Clock Skew	Measured at 1.25V for 2.5V clocks, and at 1.5V for 3.3V clocks			500	ps
t ₈	PCICLK, PCICLK	PCI-PCI Clock Skew	Measured at 1.5V			250	ps
t ₉	PCICLK, AGP	PCICLK-AGP Clock Skew	Measured at 1.5V			250	ps
t ₁₀	CPUCLK, SDRAM	Cycle-Cycle Clock Jitter	Measured at 1.25V for 2.5V clocks, and at 1.5V for 3.3V clocks			250	ps
t ₁₀	PCICLK, AGP	Cycle-Cycle Clock Jitter	Measured at 1.5V			500	ps
t ₁₁	CPUCLK, PCICLK, AGP, SDRAM	Power-up Time	CPU, PCI, AGP, and SDRAM clock sta- bilization from power-up			3	ms

Notes:

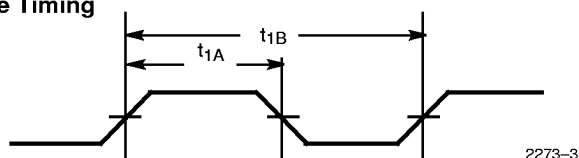
7. All parameters specified with loaded outputs.
8. Duty cycle is measured at 1.5V when V_{DD} = 3.3V. When V_{DDCPU} = 2.5V, CPUCLK duty cycle is measured at 1.25V.

Timing Requirement for the I²C Bus

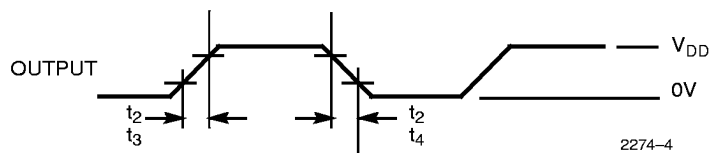
Parameter	Description	Min.	Max.	Unit
t ₁₂	SCLK Clock Frequency	0	100	kHz
t ₁₃	Time the bus must be free before a new transmission can start	4.7		μs
t ₁₄	Hold time start condition. After this period the first clock pulse is generated.	4		μs
t ₁₅	The Low period of the clock.	4.7		μs
t ₁₆	The High period of the clock.	4		μs
t ₁₇	Set-up time for start condition. (Only relevant for a repeated start condition.)	4.7		μs
t ₁₈	Hold time DATA for CBUS compatible masters. for I ² C devices	50		μs
t ₁₉	DATA input set-up time	250		ns
t ₂₀	Rise time of both SDATA and SCLK inputs		1	μs
t ₂₁	Fall time of both SDATA and SCLK inputs		300	ns
t ₂₂	Se-up time for stop condition	4.0		μs

Switching Waveforms

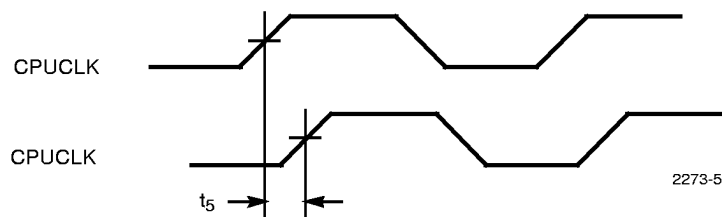
Duty Cycle Timing

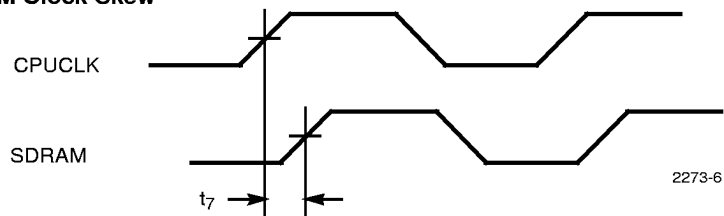


All Outputs Rise/Fall Time

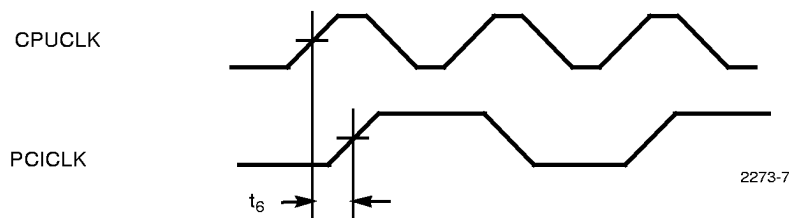


CPU-CPU Clock Skew

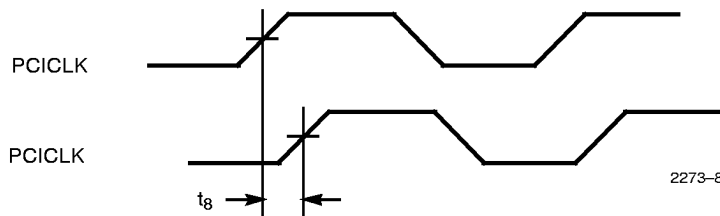


Switching Waveforms (continued)
CPU-SDRAM Clock Skew


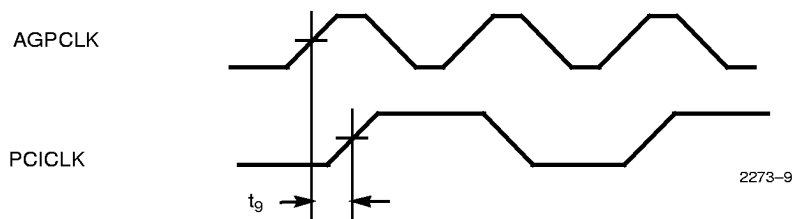
2273-6

CPU-PCI Clock Skew


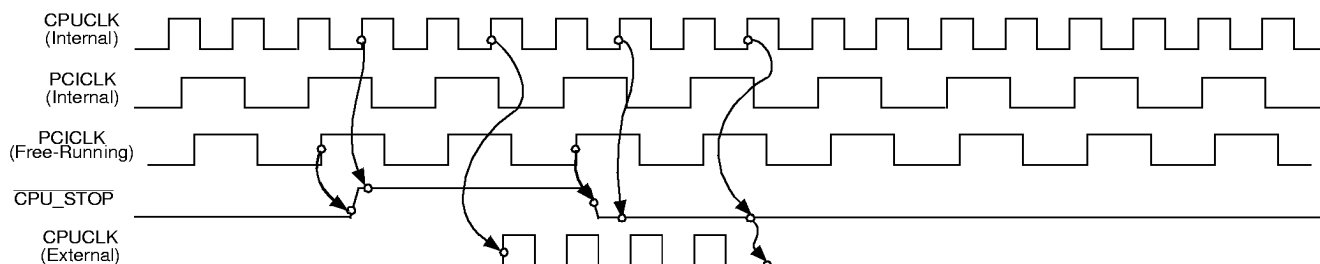
2273-7

PCI-PCI Clock Skew


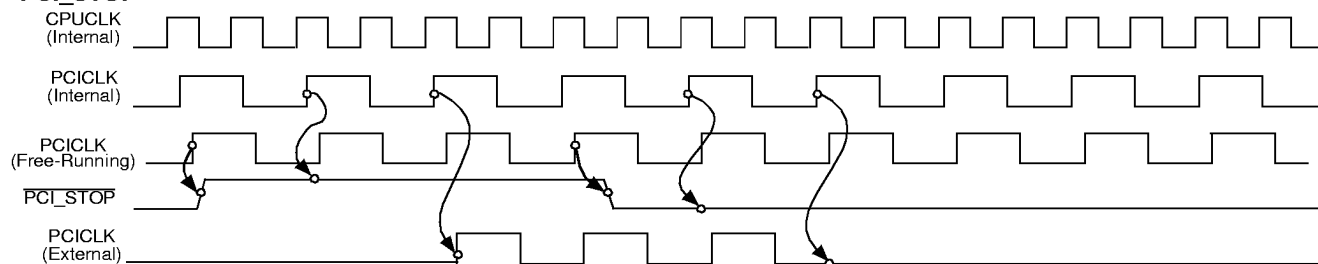
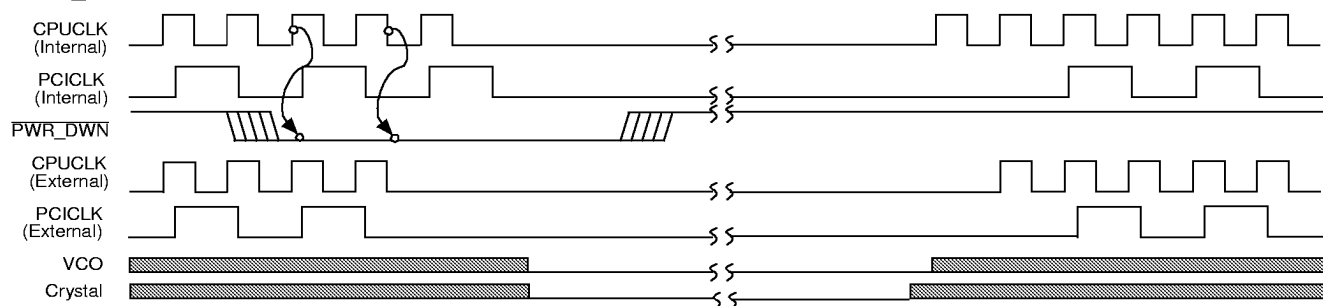
2273-8

AGP-PCI Clock Skew


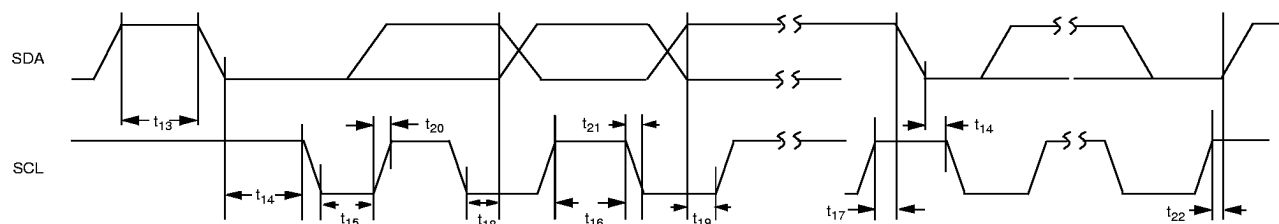
2273-9

CPU_STOP^[9, 10]

Notes:

9. CPUCLK on and CPUCLK off latency is 2 or 3 CPUCLK cycles.
10. CPU_STOP may be applied asynchronously. It is synchronized internally.

Switching Waveforms (continued)
PCI_STOP^[11, 12]

PWR_DOWN


Shaded section on the VCO and Crystal waveforms indicates that the VCO and crystal oscillator are active, and there is a valid clock.

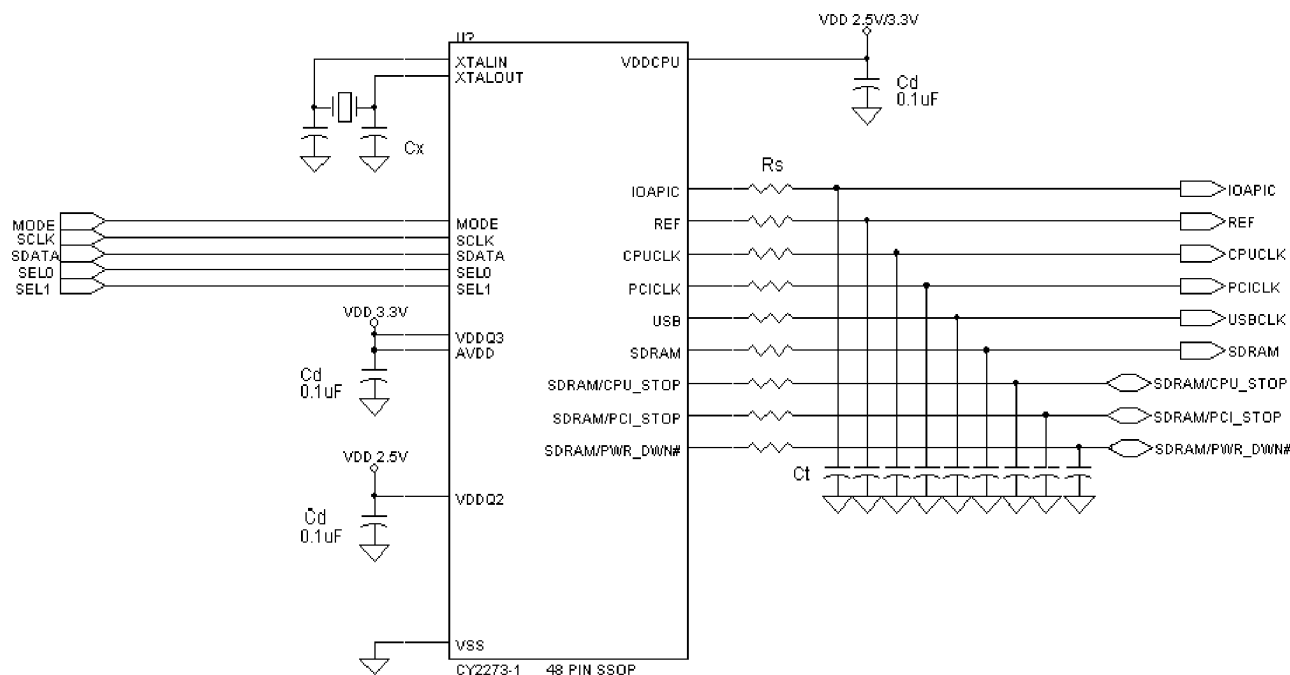
Timing Requirements for the I²C Bus

Notes:

11. PCICLK on and PCICLK off latency is 1 rising edge of the external PCICLK.
12. PCI_STOP may be applied asynchronously. It is synchronized internally.

Application Information

Clock traces must be terminated with either series or parallel termination, as they are normally done.

Application Circuit



Cd = DECOUPLING CAPACITORS

Ct = OPTIONAL EMI-REDUCING CAPACITORS

Cx = OPTIONAL LOAD MATCHING CAPACITOR

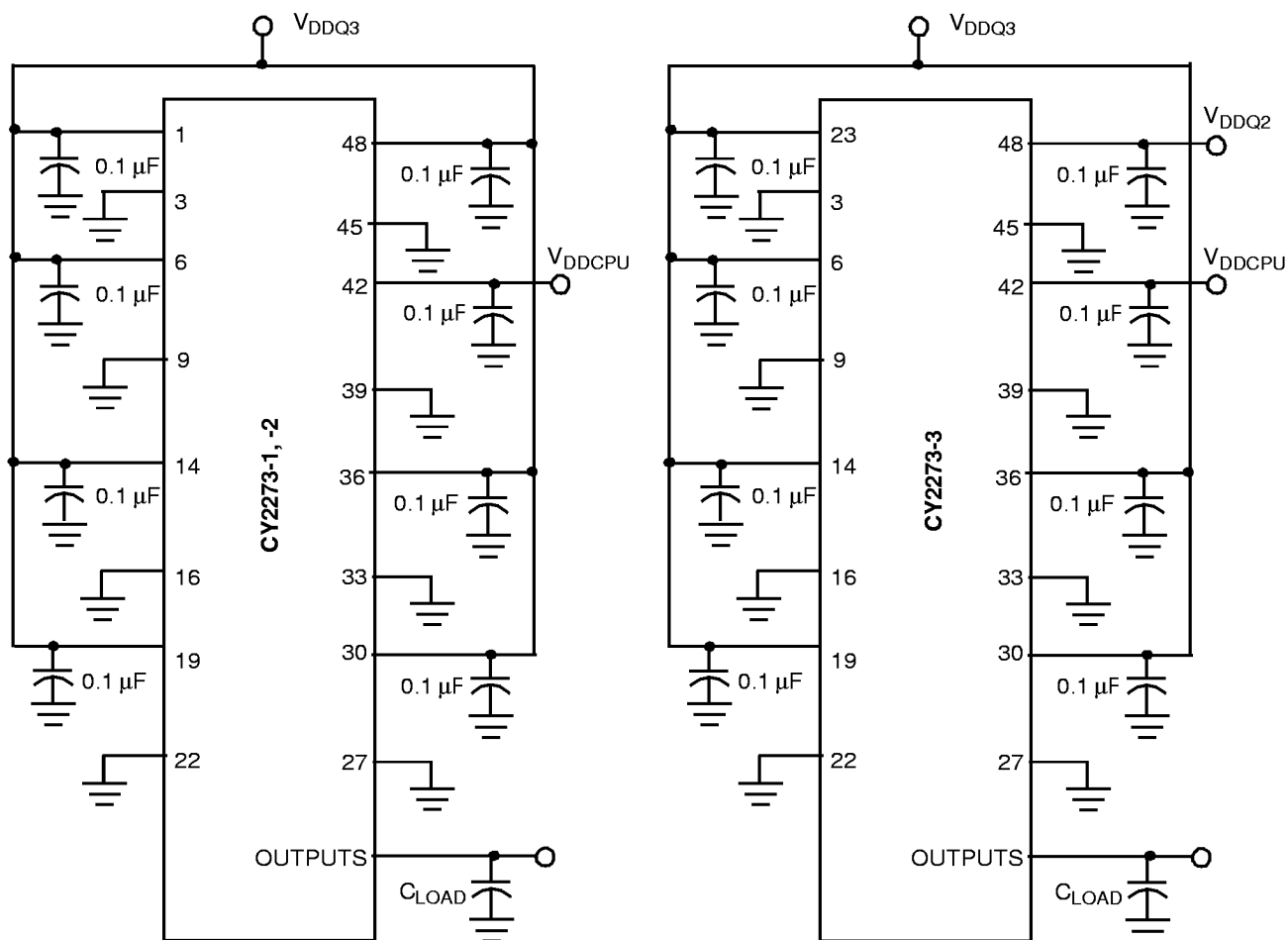
Rs = SERIES TERMINATING RESISTORS

Summary

- A parallel-resonant crystal should be used as the reference to the clock generator. The operating frequency and C_{LOAD} of this crystal should be as specified in the data sheet. Optional trimming capacitors may be needed if a crystal with a different C_{LOAD} is used. Footprints must be laid out for flexibility.
- Surface mount, low-ESR, ceramic capacitors should be used for filtering. Typically, these capacitors have a value of 0.1 μF . In some cases, smaller value capacitors may be required.
- The value of the series terminating resistor satisfies the following equation, where R_{trace} is the loaded characteristic impedance of the trace, R_{out} is the output impedance of the clock generator (specified in the data sheet), and R_{series} is the series terminating resistor.

$$R_{series} \geq R_{trace} - R_{out}$$

- Footprints must be laid out for optional EMI-reducing capacitors, which should be placed as close to the terminating resistor as is physically possible. Typical values of these capacitors range from 4.7 pF to 22 pF.
- A Ferrite Bead **may** be used to isolate the Board V_{DD} from the clock generator V_{DD} island. Ensure that the Ferrite Bead offers greater than 50 Ω impedance at the clock frequency, under loaded DC conditions. Please refer to the application note "Layout and Termination Techniques for Cypress Clock Generators" for more details.
- If a Ferrite Bead is used, a 10 μF – 22 μF tantalum bypass capacitor should be placed close to the Ferrite Bead. This capacitor prevents power supply droop during current surges.

Test Circuit


Note: All Capacitors must be placed as close to the pins as is possible

Ordering Information

Ordering Code	Package Name	Package Type	Operating Range
CY2273PVC-1	O48	48-Pin SSOP	Commercial
CY2273PVC-2	O48	48-Pin SSOP	Commercial
CY2273PVC-3	O48	48-Pin SSOP	Commercial

Document #: 38-00556-A

Package Diagram

48-Lead Shrunk Small Outline Package O48

